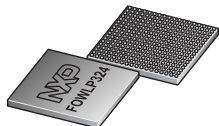


SOT2212-1

FOWLP324, fan-out wafer-level package, 324 terminals, 0.4 mm pitch, 7.3 mm x 7.3 mm x 0.725 mm body

21 November 2025

Package information



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FOWLP324
Package style descriptive code	FOWLP (fan-out wafer-level package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Manufacturer package code	98ASA02039D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.25	7.3	7.35	mm
package width	7.25	7.3	7.35	mm
seated height	-	0.725	0.76	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	324	-	

FOWLP324, fan-out wafer-level package, 324 terminals, 0.4 mm pitch, 7.3 mm x 7.3 mm x 0.725 mm body

2 Package outline

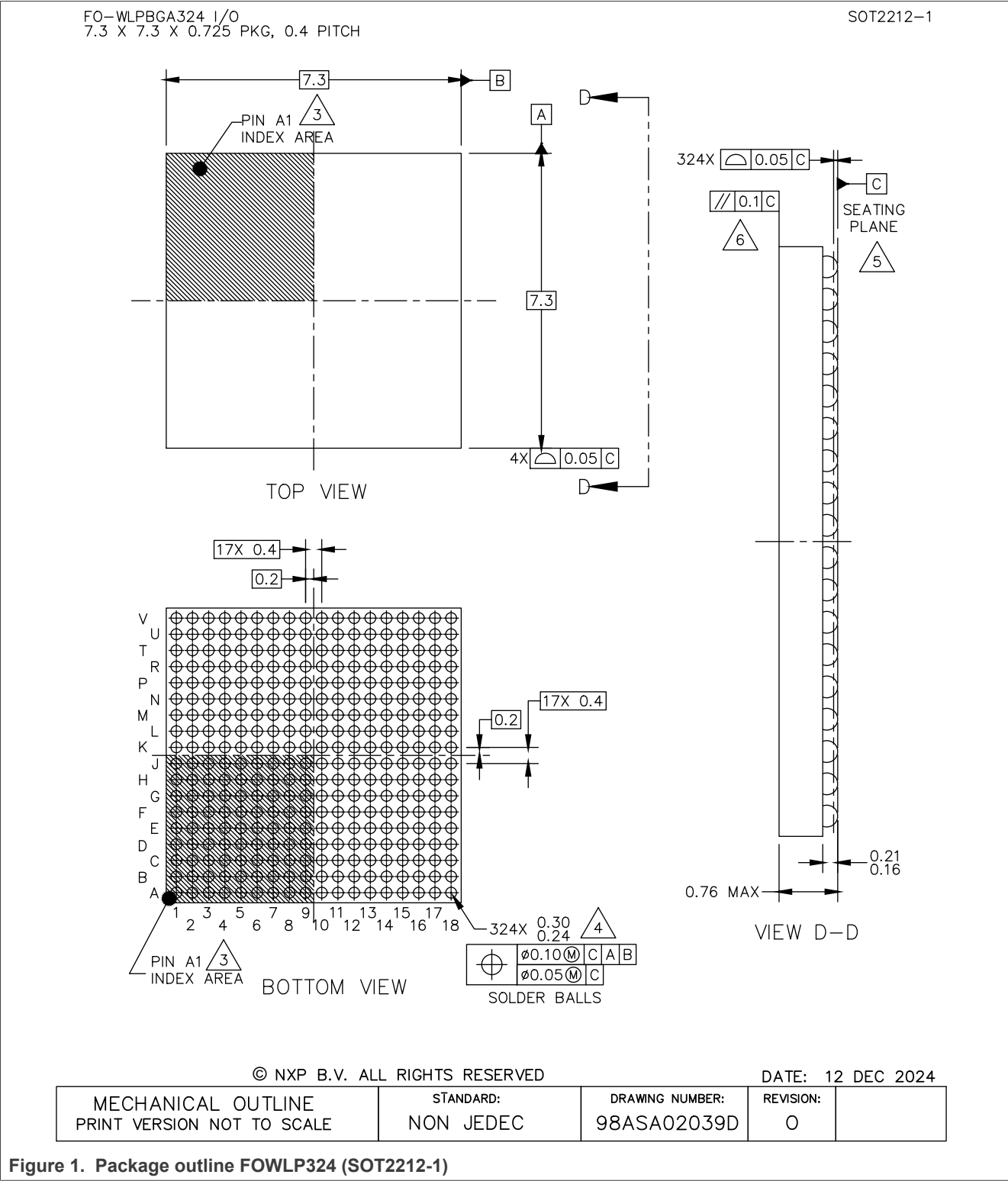
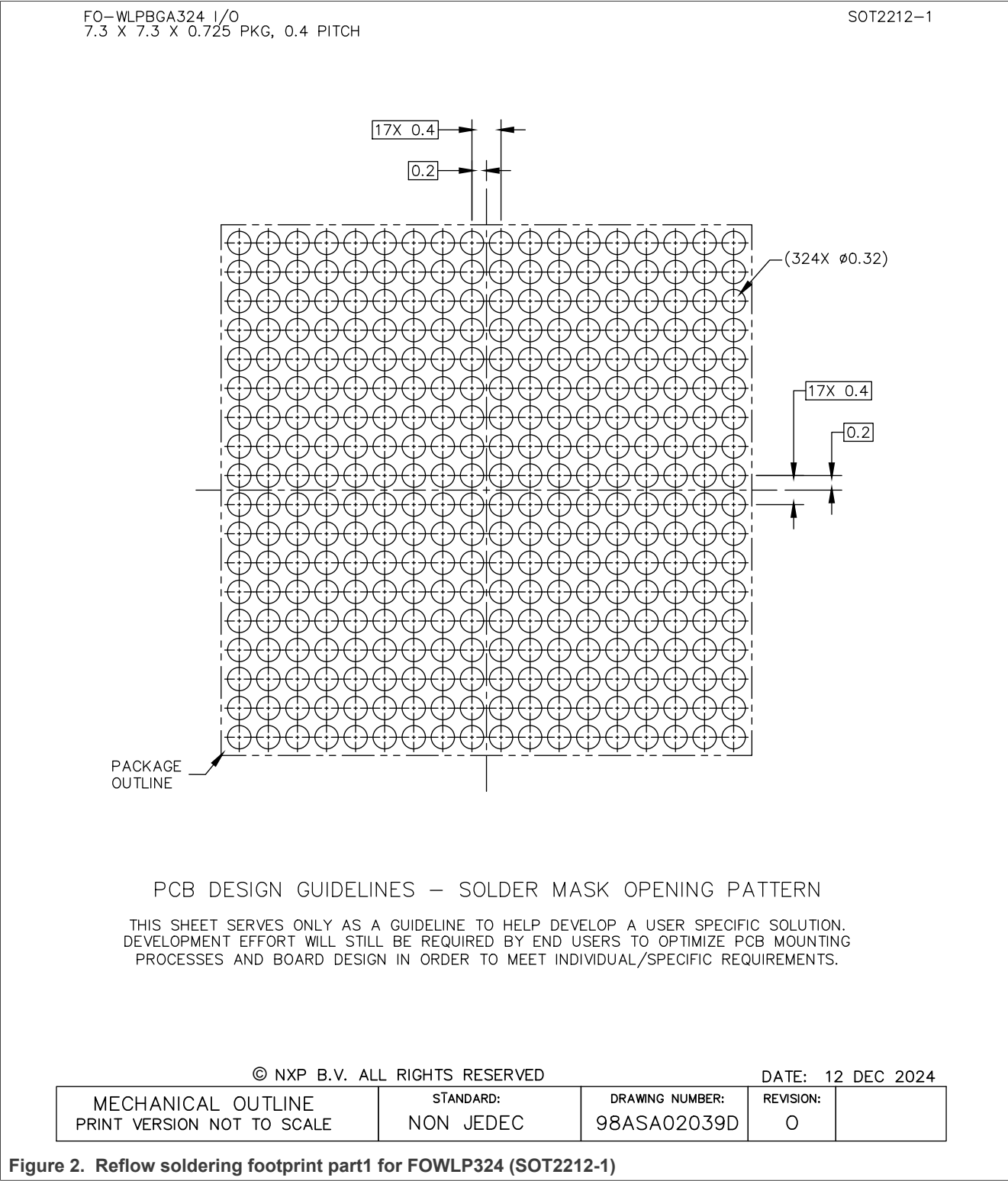


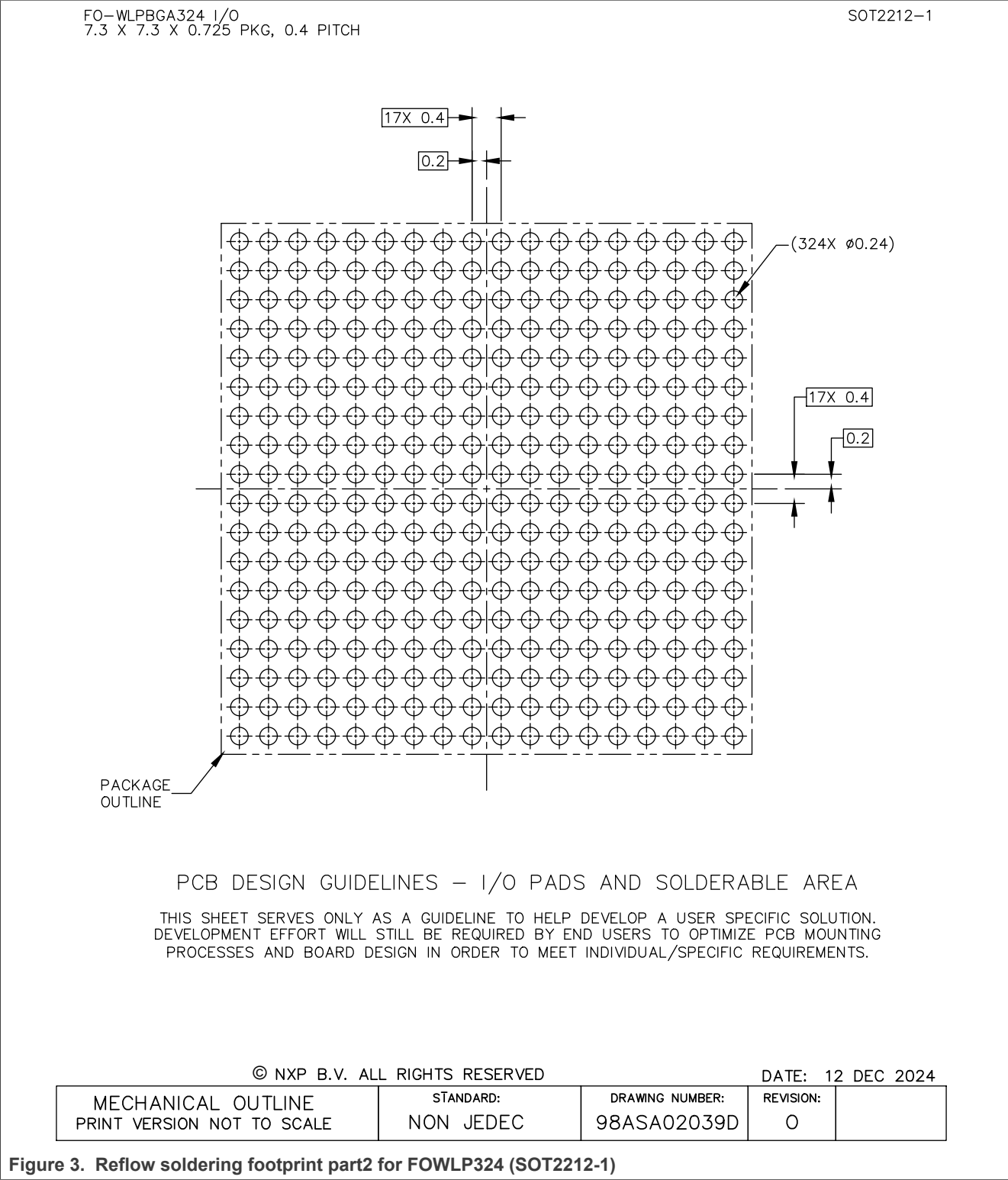
Figure 1. Package outline FOWLP324 (SOT2212-1)

FOWLP324, fan-out wafer-level package, 324 terminals, 0.4 mm pitch, 7.3 mm x 7.3 mm x 0.725 mm body

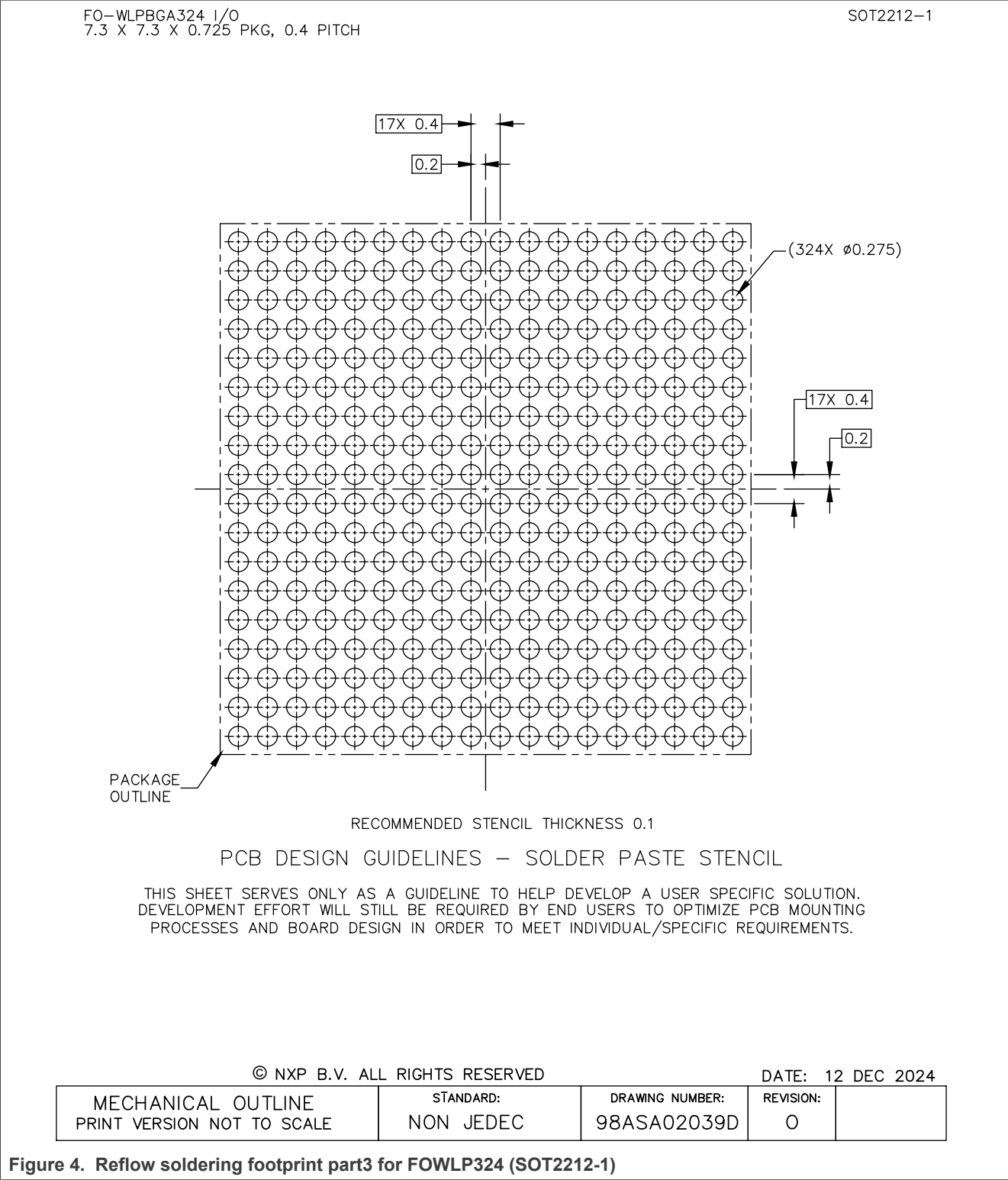
3 Soldering



FOWLP324, fan-out wafer-level package, 324 terminals, 0.4 mm pitch, 7.3 mm x 7.3 mm x 0.725 mm body



FOWLP324, fan-out wafer-level package, 324 terminals, 0.4 mm pitch, 7.3 mm x 7.3 mm x 0.725 mm body



FOWLP324, fan-out wafer-level package, 324 terminals, 0.4 mm pitch, 7.3 mm x 7.3 mm x 0.725 mm body

FO-WLPBGA324 I/O
7.3 X 7.3 X 0.725 PKG, 0.4 PITCH

SOT2212-1

- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
 - 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02039D	REVISION: 0	
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Figure 5. Package outline note FOWLP324 (SOT2212-1)

4 Legal information

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FOWLP324, fan-out wafer-level package, 324 terminals, 0.4 mm pitch, 7.3 mm x 7.3 mm x 0.725 mm body

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